

IN THE SPECIFICATION:

Please amend paragraph number [0058] as follows:

[0058] Referring now to FIG. 10, the dielectric material of layer ~~22 that~~ 24 that is exposed through each grid opening 26 and the dielectric materials of layer 22 and layer 16 may be removed from each emitter tip 14 by known processes. For example, an etchant that is selective for the dielectric materials of layer 22 and layer 16 over the material of layer 24 and over the material of emitter tip 14 may be employed to remove dielectric material through grid opening 26. When such an etchant is employed, layer 24 may be used as a mask.